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Part Number: [0475940002](#)
Status: **Active**
Description: 1.016mm (.040") by 1.016mm (.040") Pitch LGA 1366 Server CPU Socket, 0.76µm (30µ") Gold(Au) Plating, 1366 Circuits, Lead-free

Documents:

[3D Model](#) [Product Specification PS-47594-001 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family Processor Sockets
 Series [47594](#)
 Component Type Socket
 Product Name LGA1366

Physical

Circuits (Loaded) 1366
 Color - Resin Black
 Durability (mating cycles max) 30
 Material - Metal Copper Alloy
 Material - Plating Mating Gold
 Material - Plating Termination Nickel
 Material - Resin High Temperature Thermoplastic
 Packaging Type Tray
 Pitch - Mating Interface (in) 0.040 In
 Pitch - Mating Interface (mm) 1.02 mm
 Plating min: Mating (µin) 0.04
 Plating min: Mating (µm) 1.02
 Plating min: Termination (µin) 30
 Plating min: Termination (µm) 0.76
 Temperature Range - Operating -40°C to +88°C
 Termination Interface: Style Solder or Weld

Electrical

Current - Maximum per Contact 0.8A
 Voltage - Maximum 5V

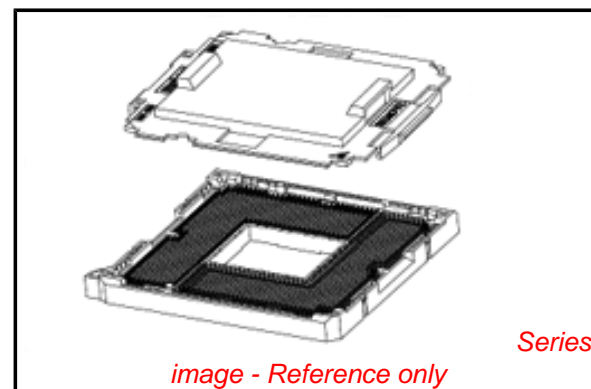
Solder Process Data

Duration at Max. Process Temperature (seconds) 3
 Lead-free Process Capability Reflow Capable (SMT only)
 Max. Cycles at Max. Process Temperature 1
 Process Temperature max. C 250

Material Info

Reference - Drawing Numbers

Packaging Specification PK-47594-001, PK-47594-003
 Product Specification PS-47594-001
 Sales Drawing SD-47594-001, SD-47594-002
 Test Summary TS-47594-001



EU RoHS

**ELV and RoHS
 Compliant**
**REACH SVHC
 Contains SVHC: No**
**Halogen-Free
 Status**

China RoHS



**Need more information on product
 environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of
 Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
 non-product compliance questions.

Search Parts in this Series
[47594Series](#)

NOTES:

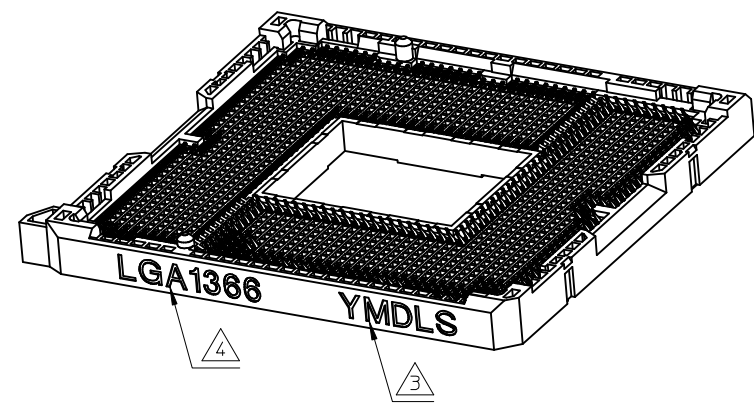
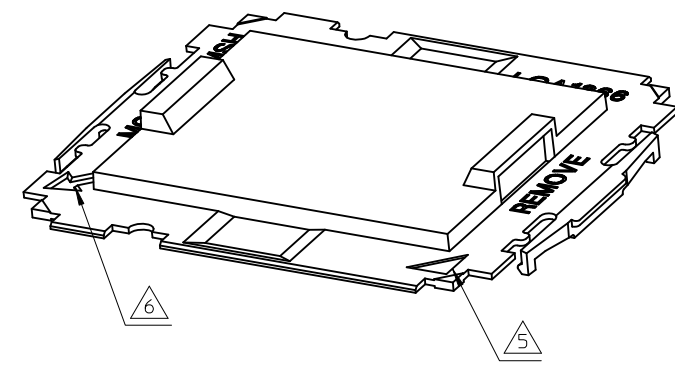
1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

SEE TABLE FOR GOLD ON CONTACT AREA.
 1.27 MICROMETER NICKEL UNDERPLATE.

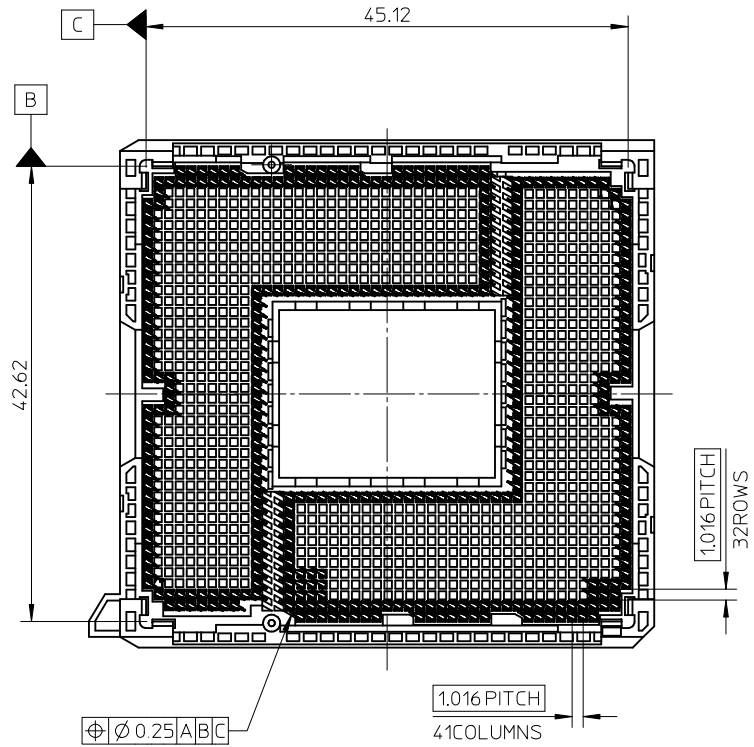
- 3. DATE-CODE LOCATION, AND DATE-CODE "YMDLS" IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)
- 4. LGA1366 TO BE INDICATED IN THIS AREA.
- 5. SOCKET PIN 1 INDICATOR.
- 6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
- 7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.
- 8. PRODUCT PACKAGE PK-47594-003 APPLIES.
- 9. THE PARTS 475940001/0002 COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.



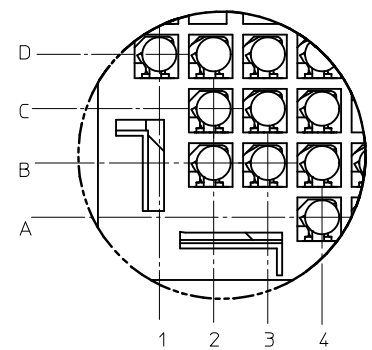
LGA1366 SOCKET PART NUMBER LIST

P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT
475940002	GENERAL	30u*(0.76um)	LEAD FREE	YES
475940001	GENERAL	15u*(0.38um)		

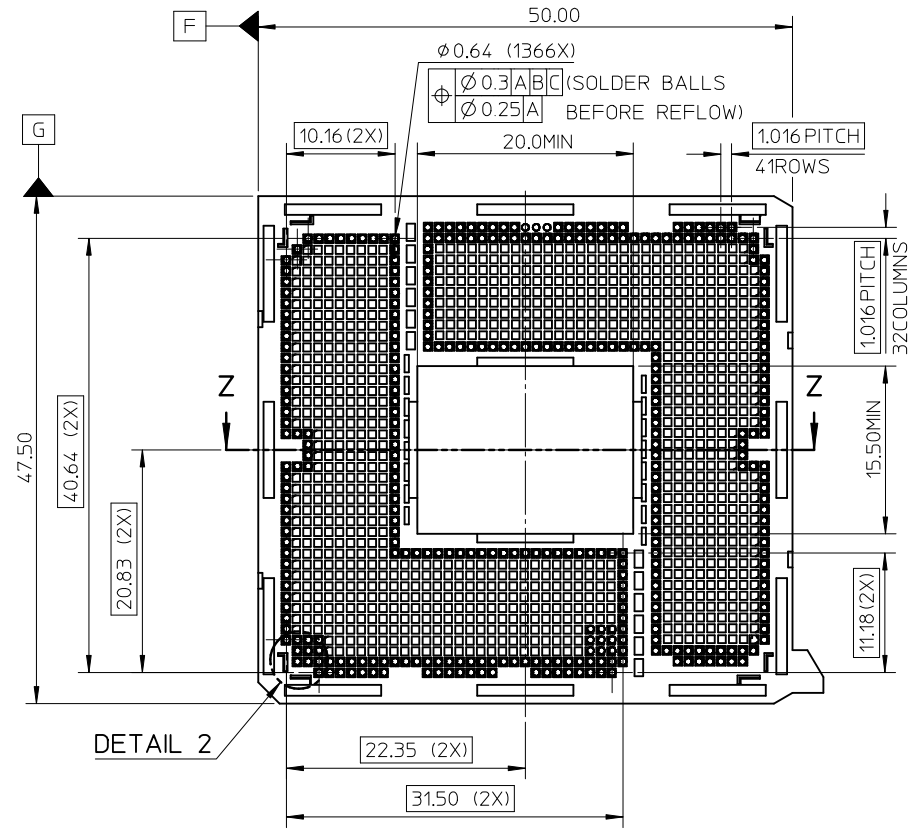
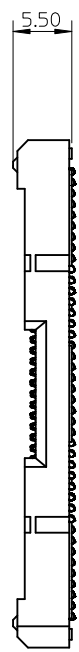
ENTER DESCRIPTION EC NO: SH2010-0161 DRWN: ZHANG11 CH'KD: 2009/10/27 APPR: WFDENG 2009/11/19	DESCRIPTION REV: A3	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 1 °	DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		▽=0		DRAWN BY WFDENG	DATE 2008/09/16	TITLE LGA1366 SOCKET FULL ASSEMBLY			
		▽E=0		CHECKED BY JKACHLIC	DATE 2008/09/16				
		▽F=0		APPROVED BY ALEX SHR	DATE 2008/09/16	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-47594-001	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



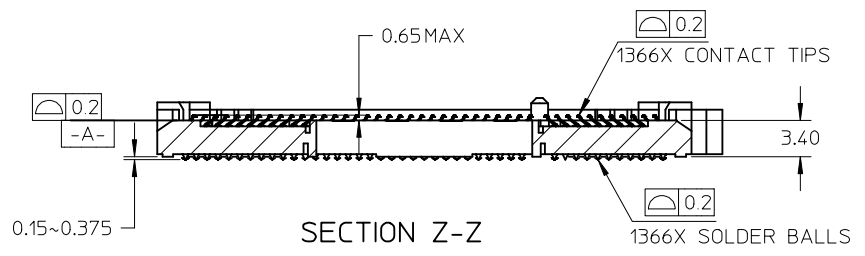
$\phi \varnothing 0.25$ ABC
 1366X CONTACT POINTS
 FOR PACKAGE LAND



DETAIL 2

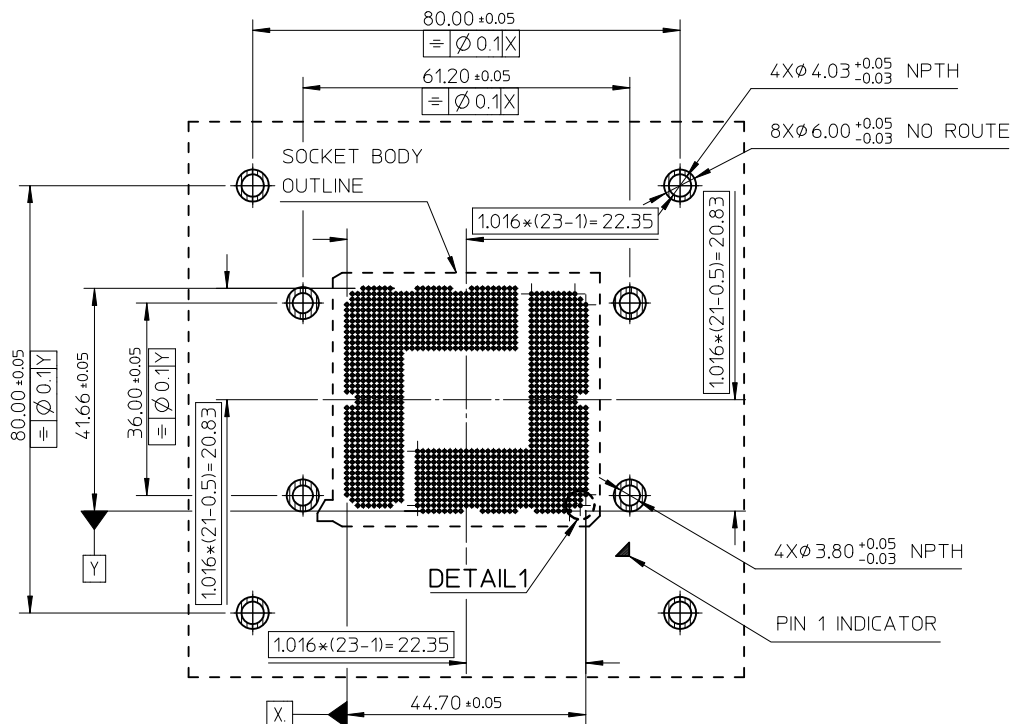


DETAIL 2

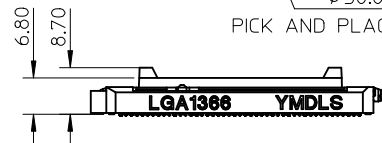
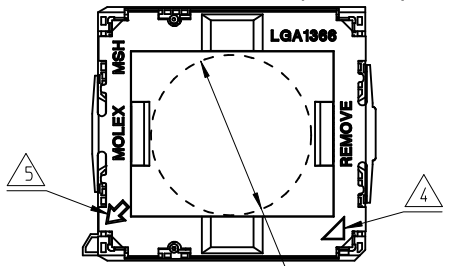


SECTION Z-Z

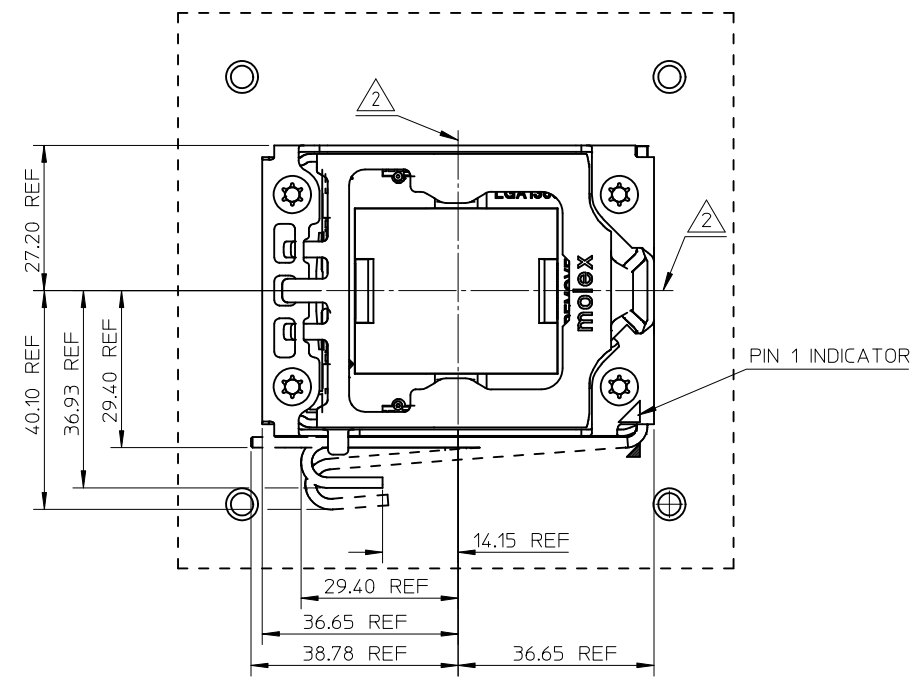
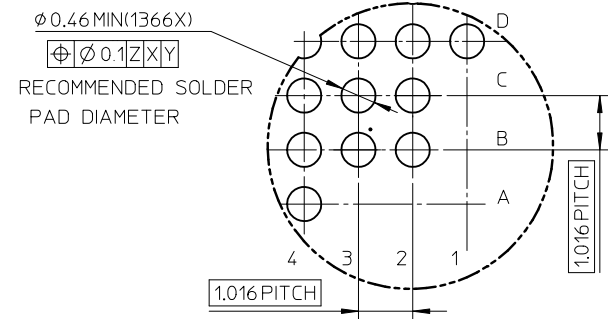
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		4 PLACES	± ---	± ---	DRAWN BY WFDENG	DATE 2008/09/16	LGA1366 SOCKET FULL ASSEMBLY MOLEX INCORPORATED			
		3 PLACES	± ---	± ---	CHECKED BY JKACHLIC	DATE 2008/09/16				
		2 PLACES	± 0.20	± ---	APPROVED BY ALEX SHR	DATE 2008/09/16				
1 PLACE	± 0.25	± ---	ANGULAR ± 1°		MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-47594-001	SHEET NO. 2 OF 3			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



RECOMMEND PCB LAYOUT
THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



- NOTES
- DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
 - GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
 - BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
 - SOCKET PIN 1 INDICATOR.
 - ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
 - ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.

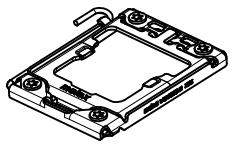
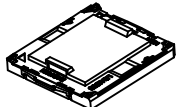
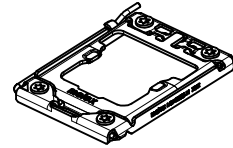
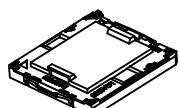
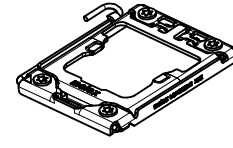
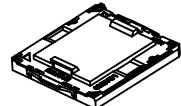
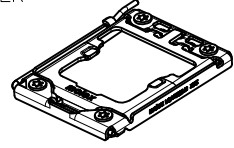
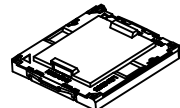


SOCKET ON PCB(FOR REFERENCE ONLY)
LOAD PLATE IS NOT LOCKED

ENTER DESCRIPTION EC NO: SH2010-0161 DRWN: JZHANG11 CHKD: 2009/10/27 APPR: WFDENG REV: A3	QUALITY SYMBOLS F=0 E=0 P=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.20 ± ---	1 PLACE ± 0.25 ± ---	ANGULAR ± 1 °	DRAWN BY WFDENG	DATE 2008/09/16	TITLE LGA1366 SOCKET FULL ASSEMBLY
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		APPROVED BY ALEX SHR		DATE 2008/09/16	MATERIAL NO. DOCUMENT NO. SD-47594-001		
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				SHEET NO. 3 OF 3	

LGA1366 SOCKET ILM KIT ASSEMBLY

SOCKET PLATING OPTIONS 47594****
 1: 15u" GOLD
 2: 30u" GOLD

<p>47594700* HOOK LEVER ILM</p>	<p>47594701* STRAIGHT LEVER ILM</p>	<p>47594800* HOOK LEVER ILM</p>	<p>47594801* STRAIGHT LEVER ILM</p>
<p>475939000 FRAME ASSEMBLY HOOK LEVER</p>  <p>LGA1366 SOCKET</p>  <p>475937000 BACK PLATE</p>	<p>475939100 FRAME ASSEMBLY STRAIGHT LEVER</p>  <p>LGA1366 SOCKET</p>  <p>475937000 BACK PLATE</p>	<p>475939000 FRAME ASSEMBLY HOOK LEVER</p>  <p>LGA1366 SOCKET</p>  <p>475938000 BACK PLATE</p>	<p>475939100 FRAME ASSEMBLY STRAIGHT LEVER</p>  <p>LGA1366 SOCKET</p>  <p>475938000 BACK PLATE</p>
<p>SERVER BACK PLATE</p>		<p>DESKTOP BACK PLATE</p>	

NOTES:




1. MATERIAL SEE COMPONENT SPECIFICATION

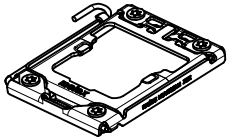
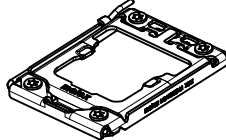
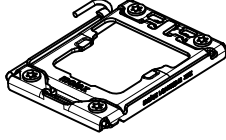
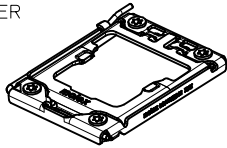
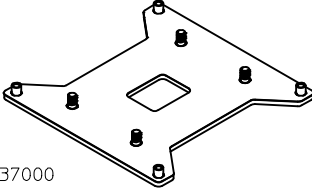
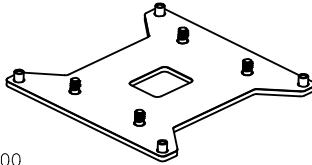
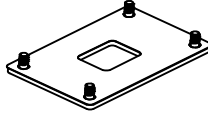
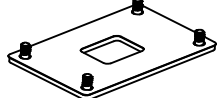
SOCKET: SD-47594-001,
 ILM FRAME ASSEMBLY: SD-47593-900,
 DESKTOP BACK PLATE: SD-47593-800,
 SERVER BACK PLATE: SD-47593-700.

2. THE PARTS 47594000X/47594800XX/47594700XX COMPLIANT TO
 RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

3. PRODUCT SPECIFICATION PS-47594-001 APPLIES.

4. PRODUCT PACKAGE PK-47594-002 APPLIES.

REVISED IEC NO: SH2009-0652 DRW:WFDENG 2009/04/17 CHKD:ZHANG 2009/04/21 APPR:CLIANG 2009/04/27 A1	QUALITY SYMBOLS  =0  =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:2	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± ---	mm INCH ± --- ± --- ± 0.20 ± --- ± 0.25 ± ---	DRAWN BY WFDENG	DATE 2008/09/16	TITLE LGA 1366 SOCKET KIT ASSEMBLY			
		ANGULAR ± 5 °		CHECKED BY JKACHLIC	DATE 2008/09/16	MOLEX INCORPORATED			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY ASHR	DATE 2008/09/25	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-47594-002	SHEET NO. 1 OF 2	

LGA1366 ILM KIT ASSEMBLY			
475940079 HOOK LEVER ILM	475940179 STRAIGHT LEVER ILM	475940089 HOOK LEVER ILM	475940189 STRAIGHT LEVER ILM
475939000 FRAME ASSEMBLY HOOK LEVER 	475939100 FRAME ASSEMBLY STRAIGHT LEVER 	475939000 FRAME ASSEMBLY HOOK LEVER 	475939100 FRAME ASSEMBLY STRAIGHT LEVER 
475937000 BACK PLATE 	475937000 BACK PLATE 	475938000 BACK PLATE 	475938000 BACK PLATE 
SERVER BACK PLATE		DESKTOP BACK PLATE	

REVISED EC NO: SH2009-0652 DRWN: WFDENG 2009/04/17 CHKD: JZHANG 2009/04/21 APPR: CLJIANG 2009/04/27 A1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± ---</td> </tr> <tr> <td colspan="3">ANGULAR ± 5 °</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± 0.25	± ---	ANGULAR ± 5 °			DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			mm	INCH																				
	4 PLACES		± ---	± ---																				
	3 PLACES		± ---	± ---																				
	2 PLACES		± 0.20	± ---																				
1 PLACE	± 0.25	± ---																						
ANGULAR ± 5 °																								
DESCRIPTION	MM ONLY	1:1	METRIC	LGA 1366 SOCKET KIT ASSEMBLY																				
	DRAWN BY	DATE	TITLE																					
	WFDENG	2008/09/16	MOLEX INCORPORATED																					
	CHECKED BY	DATE	DOCUMENT NO.																					
	JKACH LIC	2008/09/16	SD-47594-002																					
	APPROVED BY	DATE	SHEET NO.																					
	ASHR	2008/09/25	2 OF 2																					
	MATERIAL NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																						
	SEE TABLE																							